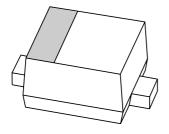
DISCRETE SEMICONDUCTORS

DATA SHEET



PMEG2010AEB

20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

Product specification

2003 Dec 03





20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

PMEG2010AEB

FEATURES

Forward current: 1.0 AReverse voltage: 20 VUltra low forward voltage

• Ultra small SMD package.

APPLICATIONS

Low voltage rectification

• High efficiency DC/DC conversion

· Voltage clamping

• Inverse-polarity protection

• Low power consumption applications.

DESCRIPTION

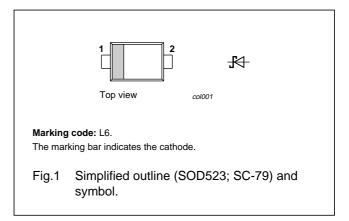
Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small plastic SMD package.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
I _F	forward current	1	Α
V_R	reverse voltage	20	V

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
I TPE NUMBER			VERSION		
PMEG2010AEB	 plastic surface mounted package; 2 leads 		SOD523		

RELATED PRODUCTS

TYPE	DESCRIPTION	FEATURE
PMEG2005EB	0.5 A; 20 V very low V _F MEGA Schottky rectifier	Lower I _R in same package
PMEG2010EA	1 A; 20 V very low V _F MEGA Schottky rectifier	Lower forward current, lower I _R SOD323 (SC76)

20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	20	V
I _F	continuous forward current	T _s ≤ 55 °C	_	1.0	А
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ ms}; \ \delta \le 0.5$	_	3.5	Α
I _{FSM}	non-repetitive peak forward current	t = 8 ms square wave	_	6	Α
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature	note 1	_	150	°C
T _{amb}	operating ambient temperature	note 1	-65	+150	°C

Note

 For Schottky barrier rectifiers, thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determination of the reverse power losses P_R and I_{F(AV)} rating will be available on request.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air; notes 1 and 2	400	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point	notes 2 and 3	75	K/W

Notes

- 1. Refer to SOD523 (SC-79) standard mounting conditions.
- For Schottky barrier rectifiers, thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determination of the reverse power losses P_R and I_{F(AV)} rating will be available on request.
- 3. Solder point of cathode tab.

20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 0.1 mA	30	60	mV
		I _F = 1 mA	80	110	mV
		I _F = 10 mA	140	190	mV
		I _F = 100 mA	230	290	mV
		I _F = 1000 mA	510	620	mV
I _R	continuous reverse current	V _R = 10 V; note 1	0.17	0.6	mA
		V _R = 20 V; note 1	0.32	1.5	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz	19	25	pF

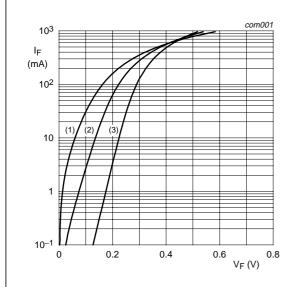
Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

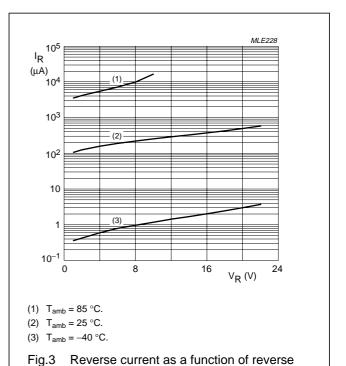
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GRAPHICAL DATA

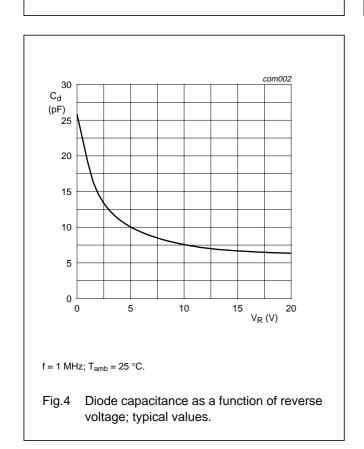


- (1) $T_{amb} = 85 \,^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -40 \, ^{\circ}C$.

Fig.2 Forward current as a function of forward voltage; typical values.



voltage; typical values.



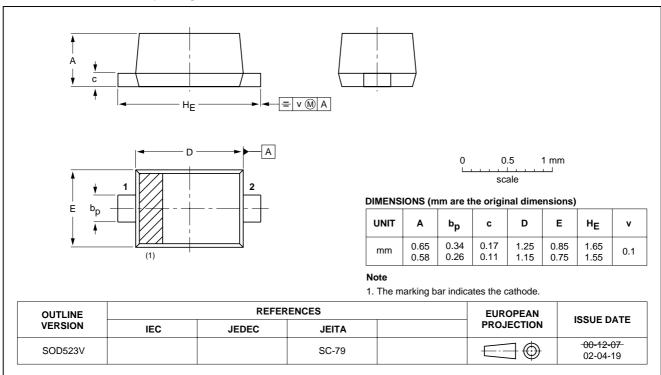
20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

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PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523V



20 V, 1 A ultra low V_F MEGA Schottky barrier rectifier in SOD523 package

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

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Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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